CUSTOMER'S NAME

ALPHA REFERENCE NO.

SP22120015

TAYDA (THAILAND) COMPANY LIMITED

SPECIFICATION

V170SF-10-15R-B5K-001	
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APPROVAL	
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PREPARED BY	REVIEWED BY	APPROVED BY
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台灣艾華電子工業股份有限公司

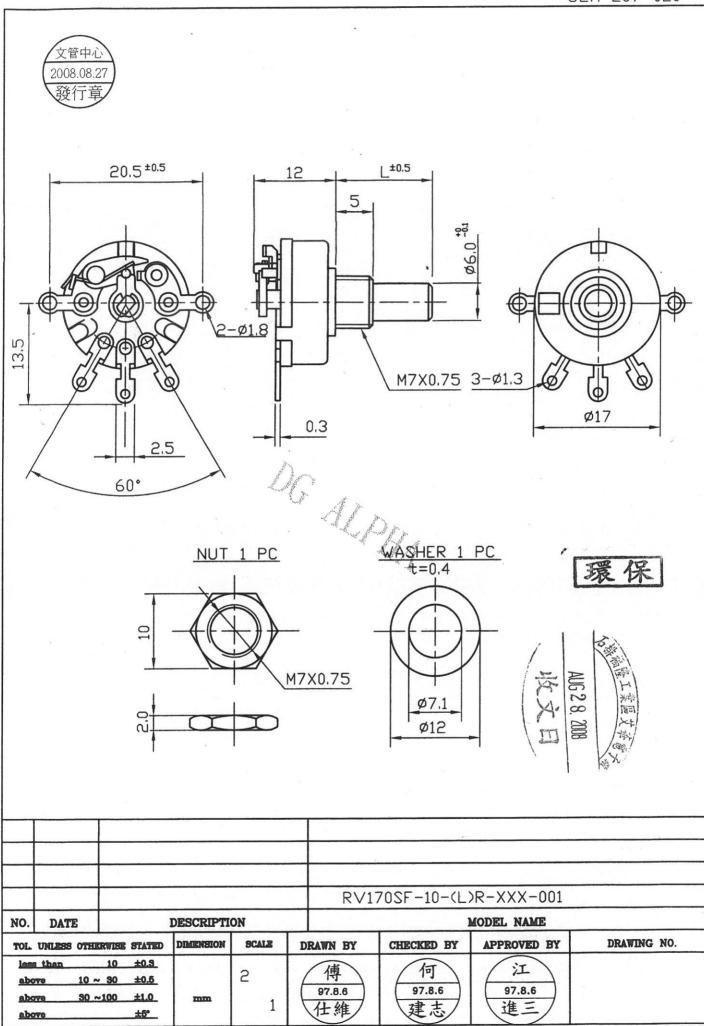
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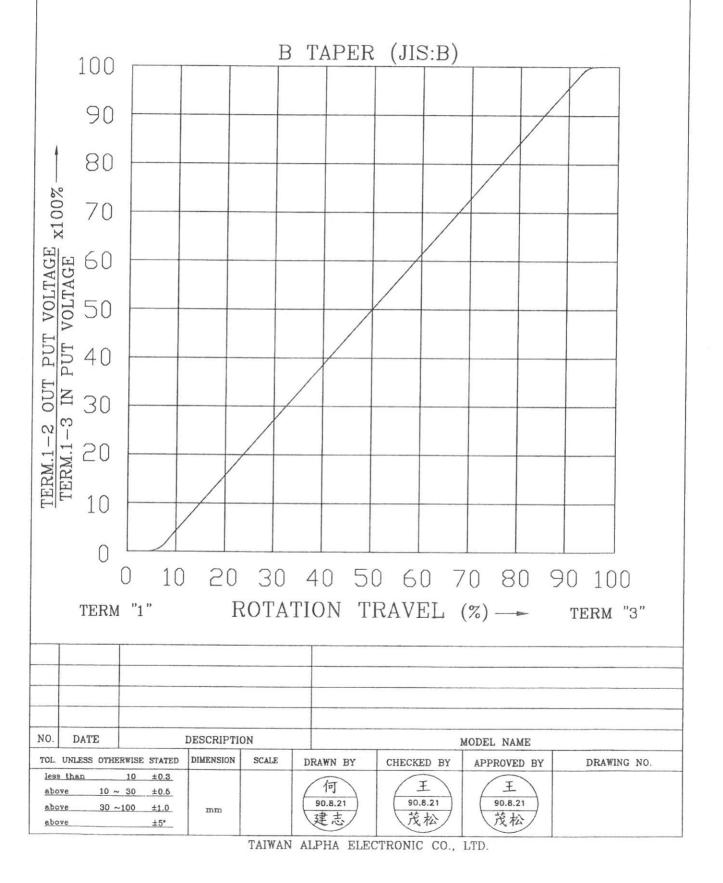
Fax: 886-3-3577700

EMAIL: sales@taiwanalpha.com.tw URL: http//www.taiwanalpha.com



:USTOMER'S NAME		NOTE			DATE		
CUSTOMER'S PART NAME							
USTOMER'S DRAWING NO.							
1. MECHANICAL SPECIFICATION	LION		2. ELECTRICAL SPECIFICATION	-			
1. OUTSIDE DIMENSION	append fig.		1. OVERALL RESISTANCE & TOLERANCE	terminal 1-3	5K	Ω± 20	%
2. TOTAL ROTATION ANGLE	degree	260 ±5°	2. TAP RESISTANCE & TOLERANCE	terminal 1-4		+G	%
3. TOTAL TRAVEL STROKE	mm	+0.5	3. RATED WATTAGE	2°05~C temp 0~50°C		0.1	
4. NUT WIRING STRENGTH	twisting moment	less than 7 kgf.cm	4. MAXIMUM WORKING VOLTAGE			200	>
5. SCREW TIGHTENING FORCE	torsional moment	less than kgf.cm	5. RESISTANCE TAPER MEASURING POINT		5	50 %point	int
6. ROTATION TORQUE	speed 60 deg/sec.	20~200 gf.cm	& TOLERANCE		40)	%
7. SLIDING FORCE	speed 20mm/sec	gf.cm	6. RESIDUAL RESISTANCE	terminal 1/3 side	less than	10/20	C
8. SHAFT LEVER STRENGTH	pulling pushing	more than kgf.cm	7. TAP RESIDUAL RESISTANCE	terminal 4 side	less than	100	C
9. SHAFT LEVER WOBBLE	within mm (bending moment	g moment gf.cm)	8. SLIDE NOISE		less than	47	νm
10. SHAFT LEVER STOP STRENGTH	more than 3 kgf.cm (static load)	tic load) / 60 sec	9. INSULATION RESISTANCE	more than 50	MOOC	200	5
	more than 500 gf.cm / 10 ± 1 sec	± 1 sec	10. WITHSTAND VOLTAGE	0	A A		. inimim
11. TERMINAL STRENGTH	soldering heat 350±5°C/3sec. 200gf.cm/10 ±1sec	00gf.cm/10 ±1sec	11. TRACKING ERROR				2
CI ICY BOSTTION & TOBOTTE	of cm		12. SWITCH CONTACT RESISTANCE	CM	less than	50 n	C
12. CLICA FOSITION & TORQUE		000	13 SWITCH RATING		17701	-	1
13. SWITCH WORKING ANGLE (STROKE)	qei	30°±10°	15. 5 WILCH INTING		12 v DC	JC , IA	
14. SWITCH WORKING TORQUE (FORCE)	gf.cm	70-400gf.cm	3 IISABI E TEMPEDATIIDE DANCE: 6 10°C 1. 70°C	TE. 6 10°C.	Z°0E		
15. SWITCH CIRCUIT		S.P.S.T	S. USABLE LEMITENALONE NAIN	GE: Irom –10 C t) N 0		
			4. VR LIFE 15,000 ±	TIMES			
SHAFT			RESISTANCE CHANGE: within ±	VGE: within ±		%	
ANGLE OF FLAT OR SLOT	OT DIMENSION	NOIS	SLIDE NOISE: less than	han		mV	
MATERIAL θ	>		SW LIFE 10,000 ±	TIMES			
			CONTACT RESISTANCE: less than	NCE: less than		Ω m	
MODEL NAME	DR/	DRAWING NO.	REFERENCE NO.		REV	_	
RV170SF-10-15R-B5K-001	-001						
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STANDARD RESISTANCE TAPER



可變電阻無鉛焊錫與保管條件共通規格書

Common Specification of Lead-Free Soldering and Storage conditions for Potentiometers

以下焊錫條件以可變電阻置於單層 1.6mm 厚度之印刷電路板上測試為基準.

The specification below is based on testing results of 1.6mm thickness single layer printed circuit board.

1. 手工焊錫條件:

For Manual Soldering:

1-1 操作溫度最高 350°C,操作時間 3 秒以內。

To be performed within 3 seconds at 350°C or below.

2. 自動或半自動機台焊錫條件:

For Automated or Semi-Automated Soldering Equipments:

2-1 使用發泡式且比重 0.82 以上的助焊劑,發泡高度以印刷電路板厚度一半為標準,且助劑不能流入可變電阻基板表面及印刷電路板表面。

Flux of 0.82 specific gravity, applied by foam fluxer, shall be used. Foam head shall be limited to the height which is half thickness of printed circuit board to be soldered. No flux should be allowed to run up onto resistive element board of potentiometer and the surface of printed circuit board.

- 2-2 預熱時間不超過兩分鐘,焊錫接面 (即印刷電路板底) 最高預熱溫度不超過 100°C。 Regarding preheating, the entire flow duration should not exceed 2 minutes, and soldering surface temperature (undersurface of PCB) shall be settled within 100°C.
- 2-3 焊錫過程機台設定溫度在 260°C 以下、 4 秒以内。
 Solder Dipping is to be performed within 4 seconds at 260°C or below.
- 3. 若回轉型電位器是塑膠軸且帶有檔位,請將主軸先調整至其中一個檔位或中心檔位上才可以 進行焊錫作業。

For rotary potentiometer with plastic shaft which have centre detent or multiple detents, the shaft should be settled in relevant detent position prior to soldering process.

4. 手工焊錫、自動或半自動機台焊錫不得超過一回。

Regardless of soldering facility and method, solder dipping or solder smearing must not be carried out more than 1 time.

註: 本項焊錫溫度條件不適用於回流焊接作業設備。

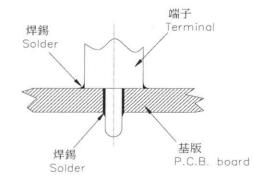
Remarks: This specification is not recommended for and applicable in reflow soldering. 焊錫注意事項:

Caution for soldering:

如圖所示,請避免 PCB 上層表面有焊錫 Please avoid soldering on upper surface of P.C.B. as shown.

5. 保管條件(Storage conditions):

產品需儲存在原始的包裝,以及保持常溫 常濕、避免陽光直射、遠離任何腐蝕性氣體. 產品需盡快完全地使用完,建議最慢不要超過



交貨後6個月.產品經折封後,全部的數量都需迅速地使用完.

The products shall be stored in the original packaging and kept at room temperature and humidity, out of direct sunlight, and away from any and all corrosive gas. The products shall be completely used as soon as possible, but no longer than 6 months from the date of delivery. Once product packaging is opened, the complete quantity of such products shall be promptly used.